

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Inventors: Su TAO et al.

U.S. Patent Application No. *Not yet assigned*

: Group Art Unit: *Not yet assigned*

Filed: *Herewith*

: Examiner: *Not yet assigned*

For: SEMICONDUCTOR CHIP PACKAGE AND METHOD FOR MANUFACTURING
THE SAME

CLAIM OF PRIORITY

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In accordance with the provisions of 35 U.S.C. 119, Applicant hereby claims the priority of *Taiwanese Patent Application No. 092104882 filed March 5, 2003*. The certified copy will be filed in due course.

Respectfully submitted,

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